

Product Change Notification / ALAN-07GWEE835

n	2	t	Δ	•
u	а	L	ㄷ	

29-Nov-2022

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5064 Final Notice: Qualification of G700LA as a new mold compound material for selected ATMEGA64xx, ATMGA16xx, ATMEGA25xx and ATMEGA32xx device families available in 64L VQFN (9x9x1.0 mm) package.

Affected CPNs:

ALAN-07GWEE835_Affected_CPN_11292022.pdf ALAN-07GWEE835_Affected_CPN_11292022.csv

Notification Text:

Notification Body:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700LA as a new mold compound material for selected ATMEGA64xx, ATMGA16xx, ATMEGA25xx and ATMEGA32xx device families available in 64L VQFN (9x9x1.0 mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)				
Wire Material	Au/Cu/PdCu	Au/Cu/PdCu				
Die Attach Material	EN-4900GC	EN-4900GC				
Molding Compound Material	CEL-9240	G700LA				
Lead-Frame Material	C194	C194				
Lead-Frame Paddle Size	228x228/ 311x311	228x228/ 311x311				
DAP Surface Prep	Ring/ Double Ring	Ring/ Double Ring				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying G700LA as new mold compound material.

Change Implementation Status:In Progress

Estimated First Ship Date:December 23, 2022 (date code: 2252)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2022				>	November 2022			December 2022						
Workweek	1 0	1 1	1 2	1 3	1 4		4 5	4 6	4 7	4 8	4 9	5 0	5 1	52	53
Initial PCN Issue Date		Х													
Qual Report Availability											Χ				
Final PCN Issue Date											Χ				
Estimated Implementation Date														Χ	

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 10, 2022: Issuance of Initial notification.

November 29, 2022: Issuance of Final notification. Attached Qual Report and added estimated first ship date on December 23, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-07GWEE835 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

ALAN-07GWEE835 - CCB 5064 Final Notice: Qualification of G700LA as a new mold compound material for selected ATMEGA64xx, ATMGA16xx, ATMEGA25xx and ATMEGA32xx device families available in 64L VQFN (9x9x1.0 mm) package.

Affected Catalog Part Numbers (CPN)

ATMEGA645P-MU

ATMEGA649A-MU

ATMEGA645A-MU

ATMEGA649P-MU

ATMEGA649A-MUR

ATMEGA645P-MUR

ATMEGA645A-MUR

ATMEGA649P-MUR

ATMEGA169P-16MU

ATMEGA169PV-8MU

ATMEGA165PV-8MU

ATMEGA169P-16MUR

ATMEGA169PV-8MUR

ATMEGA165PV-8MUR

ATMEGA169PV-8MURA1

ATMEGA325P-20MU

ATMEGA329PV-10MU

ATMEGA329P-20MU

ATMEGA329PV-10MN

ATMEGA329P-20MN

ATMEGA329P-20MNR

ATMEGA329P-20MUR

ATMEGA329PV-10MUR

ATMEGA2561V-8MUA0

ATMEGA2561V-8MURA0